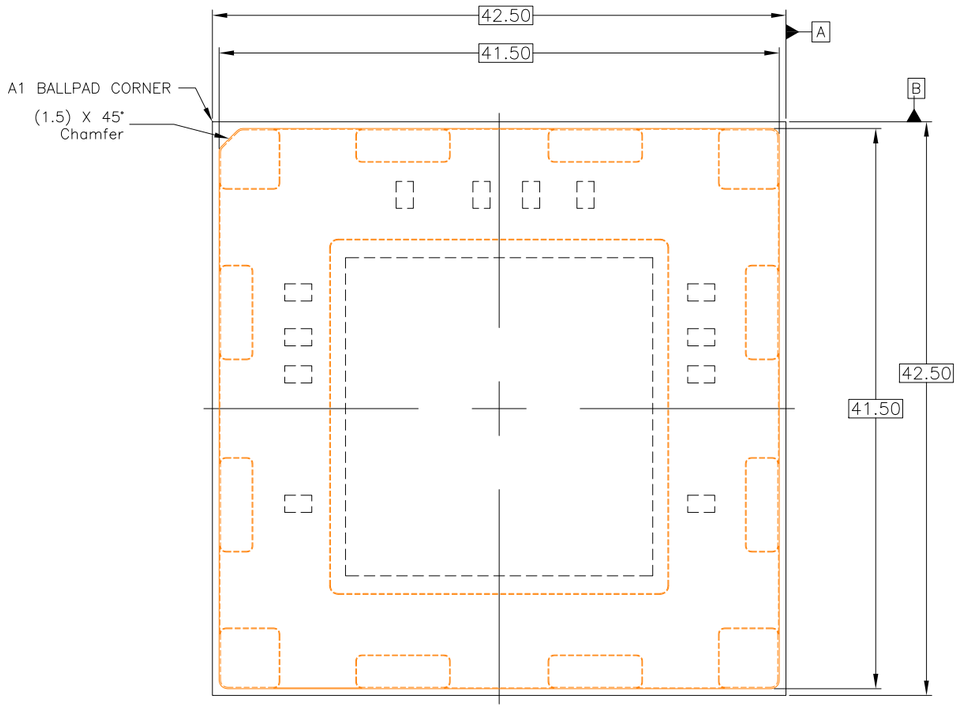
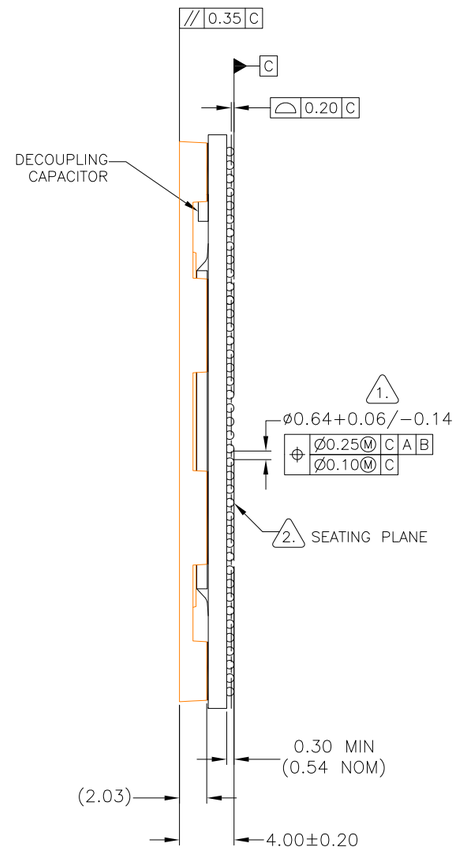
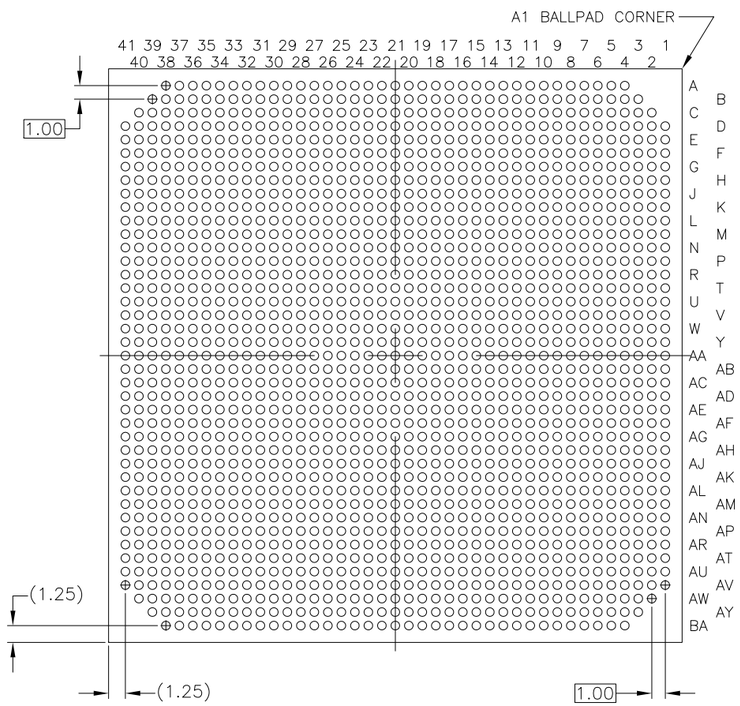
ECN NO.	REV.	DESCRIPTION OF CHANGE	ECN DATE	ORIGINATOR
20190108	0	Preliminary Drawing	12/14/18	Erwin Q.
20200074	1	Revise title from RT4G150M-FCG1657 to RT4G150-FCG1657M, add vendor dwg #.	02/24/20	Erwin Q.



TOP VIEW



SIDE VIEW



BOTTOM VIEW
1657 Solder Balls

NOTES:

1. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.
2. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

GENERAL TOLERANCE
UNLESS OTHERWISE SPECIFIED
DECIMAL
X.X ±0.1
X.XX ±0.05
X.XXX ±0.030
ANGULAR
±1°
INTERPRET DIM AND TOL PER ASME Y14.5M – 2009

DIMENSIONS: Millimeters (mm)

PROJECTION:

APPROVALS	DATE
DRAWN: Erwin Q.	02/24/20
CHECKED: Raymond K.	02/24/20
ENG'R:	
RELEASED:	

Microsemi®
MICROSEMI CORPORATION, SOC GROUP
3850 N 1st St
San Jose, CA 95134

TITLE: RT4G150-FCG1657M, 42.5 MM X 42.5 MM, 1.0 MM PITCH, 1657 SOLDER BALLS, FLIP CHIP, PACKAGE OUTLINE DRAWING

VENDOR NAME:	DWG. NUMBER:	REV:
Amkor Technology	1-14-12021	1
PART NUMBER: --	VENDOR DWG. NUMBER: 0851877PO	REV: D

SCALE: NONE | SHEET 1 OF 1

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